

# PATENT ASSIGNMENT

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NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Tetsuya Ohsawa	11/11/2005
Yasuhito Funada	11/11/2005
Hitoki Kanagawa	11/11/2005
RECEIVING PARTY DATA	
Name:	Nitto Denko Corporation
Street Address:	1-2, Shimohozumi 1-chome
City:	Ibaraki-shi, Osaka
State/Country:	JAPAN
Postal Code:	567-8680
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11256800
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NAME OF SUBMITTER:	John Kilyk, Jr.
Total Attachments: 2	
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**PATENT**  
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Attorneys at Law  
Two Prudential Plaza  
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Chicago, Illinois 60601-6780

**ASSIGNMENT OF APPLICATION FOR PATENT**

**WHEREAS, WE,**

Tetsuya OHSAWA of c/o Nitto Denko Corporation, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka  
567-8680 Japan

(full name and address, including postal code, of first inventor)

Yasuhito FUNADA of c/o Nitto Denko Corporation, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka  
567-8680 Japan

(full name and address, including postal code, of second inventor)

Hitoki KANAGAWA of c/o Nitto Denko Corporation, 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka  
567-8680 Japan

(full name and address, including postal code, of third inventor)

respectively, have invented and own a certain new and useful invention entitled:

**SUSPENSION BOARD WITH CIRCUIT**

for which invention we have executed an application for Letters Patent of the United States which was filed  
on October 24, 2005, under Serial No. 11/256,800; and

**WHEREAS,**

Nitto Denko Corporation of 1-2, Shimohozumi 1-chome, Ibaraki-shi, Osaka 567-8680 Japan

(full name and address, including postal code, of assignee)

(hereinafter referred to as Assignee) is desirous of acquiring the entire right, title, and interest in and under the invention described in the application for Letters Patent.

**NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:** Be it known that for good and valuable considerations, the receipt and sufficiency of which are hereby acknowledged, we have assigned and set over, and by this document do assign and set over, to the Assignee and the Assignee's legal representatives, successors and assigns the entire right, title, and interest in and to the invention in the United States the applications for Letters Patent and other such applications (e.g., continuations, continuations-in-part, divisionals and reissues) in the United States, and the Letters Patent, or extensions thereof, that may or shall issue thereon; and we do hereby authorize and request the Commissioner of Patents and Trademarks to issue the Letters Patent to the above-mentioned Assignee agreeably with the terms of this Assignment.

**WE HEREBY AUTHORIZE** the above-mentioned Assignee to insert in this assignment document the filing date and serial number of the application if the date and number are unknown at the time this assignment is executed.

WE DO HEREBY COVENANT and agree with the Assignee that we will not execute any writing or do any act whatsoever conflicting with the terms of this assignment document set forth herein, and that we will at any time upon request, without further or additional consideration, but at the expense of the Assignee, execute such additional assignments and other writings and do such additional acts as the Assignee may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, continuation, renewal, reissued, or extended Letters Patent of the United States or of any and all foreign countries on the invention, and in enforcing any rights or choses in action accruing as a result of such applications or patents, and by executing preliminary statements and other affidavits, it being understood that the foregoing covenant and agreement shall bind, and inure to the benefit of, the assigns and legal representatives of both parties.

IN WITNESS WHEREOF, we have hereunder set our hands on the dates shown below:

Tetsuya Ohsawa  
Signature of First Inventor      Tetsuya OHSAWA

November 11, 2005  
Date

Yasuhito Funada  
Signature of Second Inventor      Yasuhito FUNADA

November 11, 2005  
Date

Hitoki Kanagawa  
Signature of Third Inventor      Hitoki KANAGAWA

November 11, 2005  
Date

Yutaka Aoki  
Witness      Date  
Yutaka AOKI      November 11, 2005

Koichiro Tada  
Witness      Date  
Koichiro TADA      November 11, 2005

Yutaka Aoki  
Witness      Date  
Yutaka AOKI      November 11, 2005

Koichiro Tada  
Witness      Date  
Koichiro TADA      November 11, 2005

Yutaka Aoki  
Witness      Date  
Yutaka AOKI      November 11, 2005

Koichiro Tada  
Witness      Date  
Koichiro TADA      November 11, 2005